



Co-located with



productronica 2017

## Key Visiting Companies

- A&T
- ABB Semiconductors
- AT&S AG
- Avago/Broadcom
- BMW AG
- Bosch
- Boston Scientific
- CEA LETI
- Continental AG
- Crocus Nanoelectronics
- Daimler AG
- Denso Automotive Deutschland GmbH
- Dialog Semiconductor
- DigiMatrix GmbH
- DYLAN-TEK CO., Ltd.
- Dyne Semiconductor
- ELMOS Semiconductor AG
- Eolane Tallinn
- EPCOS AG
- Fagor Electronica
- Fingerprint Cards AB
- Fraunhofer EMFT
- Fraunhofer IMS
- Fraunhofer IOF
- Fraunhofer IZM
- GLOBALFOUNDRIES
- Henkel Ltd.
- Hitachi Automotive Systems
- Honda Engineering Europe Ltd.
- Honeywell
- Hortech Company
- Infineon Technologies AG
- Institut Laue-Langevin
- Institute of Nanotechnology
- Intel
- Jabil Inc.
- Korea Electronic Technology Institute
- LFoundry
- Linde Electronics GmbH & Co. KG
- Lintec Advanced Technologies
- Logitech UK Ltd.
- Magna Electronics
- Magneti Marelli GmbH
- Max-Planck Institute Polymer Research
- Memscap AS
- memsfab GmbH
- memsstar Limited
- Merck Ventures
- Microoled
- Mikron PJSC
- Murata Electronics
- NANIUM S.A—Amkor Technology
- Nexperia Germany GmbH
- Nike, Inc.
- NIKON Corporation
- NXP Semiconductors
- ON Semiconductor
- OpenATE Inc.
- OSRAM Opto Semiconductor
- PALL Corporation
- Philips GmbH
- Photonics Research Center
- Qualcomm Germany RFFE GmbH
- Robert Bosch GmbH
- Samsung Electronics
- Samsung Semiconductor
- Samtec Microelectronics
- Schneider Electric
- Sensata Technologies
- Sensirion AG
- Siemens AG
- Sierra Wireless Inc.
- Sigfox
- Silex Microsystems AB
- Sofradir
- SOITEC
- Sony Europe Ltd.
- Star Electronica, SLL
- STMicroelectronics
- Sunedison Semiconductor
- Swiss Innovation Lab AG
- TDK Epcos OHG
- TE Connectivity Sensor Germany GmbH
- TEL Venture Capital
- Teledyne e2v GmbH
- Telit Wireless Solutions Ltd.
- Texas Instruments
- United Monolithic Semiconductors
- Vishay Semiconductor GmbH
- VOLVO
- VTT Technical Research Centre
- X-FAB MEMS Foundry GmbH
- Xcerra Corporation

# CONNECT

## SEMICON® Europa 2017

14-17 November, 2017 Messe München, Munich Germany

### 2017 Highlights:

- **First-time Co-location with productronica** attracted more than 44,000 visitors from 85 Countries
- **Largest Semiconductor Manufacturing Event in Europe:** More than 8,700 industry experts, professionals and executives in attendance
- **Executive Keynote Speakers:**
  - Dr. Stefan Finkbeiner, CEO, *Bosch Sensortec*
  - Maria Marced , President, *TSMC Europe*
  - Carlos Mazure, EVP and CTO, *Soitec*
  - Frank M. Rinderknecht, Founder and CEO, *Rinspeed Inc.*
- **More than 250 Speakers Featured** in more than 40 conferences, sessions, and workshops, including:
  - **Fab Management Forum**
  - **Advanced Packaging Conference**
  - **2017FLEX Europe/Be Flexible Conference**
  - **Materials Conference**
  - **Power Electronics Conference**
- **More than 1,000 Program and Conference Attendees**
- **34 Media Partners, 30 Supporting Institutions**

### Attendance

<b>Total Attendance (SEMICON and productronica)</b>	<b>~44,000</b>
<b>Verified SEMICON Europa Visitors</b>	<b>8,781</b>

### Exhibitor Information

<b>Total Exhibiting Companies</b>	<b>353</b>
<b>Net Exhibit Area (sqm)</b>	<b>4,780</b>

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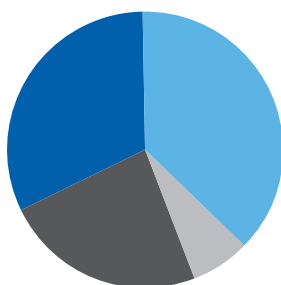


## Visitor Profile

SEMICON Europa attracts a highly influential audience from every segment and sector of the European micro-electronics industries including materials, front-end and final manufacturing, and advanced packaging, as well as from product and application markets including semiconductor, MEMS, sensors, power electronics, flexible electronics, IoT, automotive, medtech, and others.

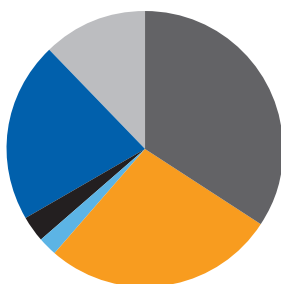
### Influential Buyers

More than 70% of SEMICON Europa visitors are involved in purchasing decisions, influencing the selection and final purchase of microelectronics manufacturing equipment, materials, software, and services.



#### PURCHASING AUTHORITY

- 32% Final Decision Maker
- 38% Recommend/Evaluate/Consult
- 7% Specify
- 24% No Role



#### JOB LEVELS

- 21% Executive Management
- 12% Senior Management
- 34% Other Management
- 27% Staff/Professional
- 2% Student
- 3% Other

35% visitors represent engineering job functions

### Primary Job Functions

SEMICON Europa attracts multi-level buying teams, with broad representation across all levels, functions and industries.

<b>Design Engineering</b> (incl. Software, Systems, Test, Hardware)	15%
<b>Fabrication and Process Engineering</b>	12%
<b>Assembly/Packaging Engineering</b>	6%
<b>Chemical Engineering</b>	2%
<b>Executive Management/Board Member</b>	19%
<b>Marketing, Sales, Business Development</b>	15%
<b>Product Operations Management</b>	12%
<b>Manufacturing and Production</b>	8%
<b>Purchasing/Procurement</b>	4%
<b>Training/Educator</b>	1%
<b>Environment, Health and Safety (EHS)</b>	<1%
<b>Financial/Industry Analyst</b>	<1%
<b>Government/Public Policy/Investor Relations</b>	<1%
<b>Human Resources</b>	<1%
<b>Other</b>	5%



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## Areas of Interest

SEMICON Europa visitors are interested in a broad range of industries, technologies, and products from across the supply chain, from design to final manufacturing.

### Segment/Application Interests

Semiconductors/Compound Semiconductors	36%
Automotive Electronics	34%
Electronics Applications	28%
Power Electronics	25%
Smart Manufacturing/Automation/Robotics	24%
LED/Solid State Lighting	22%
MEMS and Sensors/Nanoelectronics	21%
Internet of Things (IoT)	17%
Flexible Hybrid Electronics (FHE)/Printed Electronics	15%
Medical Electronics/MedTech	15%
Photovoltaics (PV)	13%
Wearables/Consumer Electronics	11%
Displays	9%

### Product/Technology Areas of Interest

#### MANUFACTURING

Electronic Manufacturing Services (EMS)	44%
Packaging Assembly and Test Services	27%
Semiconductor Device Manufacturing (IDM, foundry)	23%
LED Manufacturing	17%
Fabless Semiconductor Manufacturer	10%
Other Manufacturing	13%

#### EQUIPMENT

Assembly and Packaging	34%
Inspection and Measurement/Metrology	31%
Factory Automation/Robotics	28%
Test	28%
Printing, Coating, Roll-to-Roll Equipment	20%
Wafer Processing/Front-end	19%
Secondary	3%
Other Equipment	11%

#### MATERIALS

Assembly and Packaging Materials	30%
Consumables (test and process)	21%
Wafer and Silicon Related Substrates	20%
LED/MEMS/PV/Display Materials	17%
Inks, Pastes and Printing	14%
Photolithography/Deposition Materials	14%
Gases, Liquids, Chemicals, Solids	13%
Other Materials	14%

#### SUB-SYSTEMS/COMPONENTS/OTHER

R&D/Technology Transfer	13%
Manufacturing Services and Consulting (directly related to mfg.)	12%
Electronic Components and Instrumentation	11%
Sub-systems	11%
Key Component and Others, Laser Source	8%
General Business Service/Consulting	7%
Outsourced Manufacturing	5%
Other	1%

#### DESIGN

Software/EDA/Modeling	21%
Fabless	9%
Other Design/Software	28%

Percentages based on total verified SEMICON Europa visitors

